



BP2

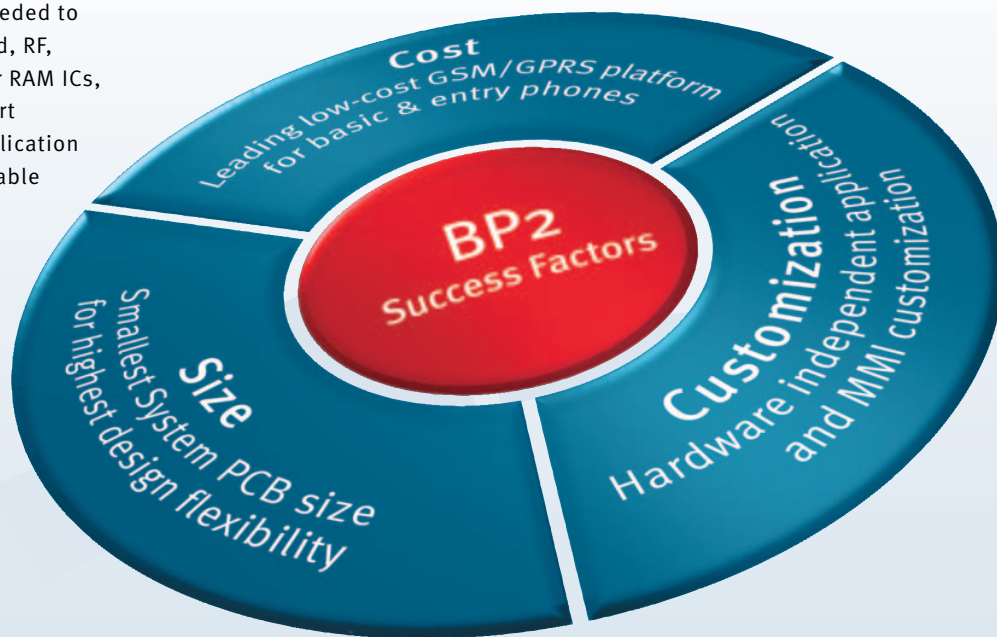
Entry & Basic Platform

Infineon's cost-optimised GSM/GPRS platform BP2 is one of the highest integrated and most complete system solutions available today. It allows customers to develop and market mobile phones in record time.

Included are all components needed to build a mobile phone: baseband, RF, power management and cellular RAM ICs, complemented by state of the art protocol stack, the APOXI™ application framework and a fully customizable Man-Machine-Interface (MMI)

Infineon's development environment offers development boards, a comprehensive tool chain and a SDK for the application framework. Customers will also benefit from Infineon's extensive experience with chipsets and complete customized solutions in the mobile market.

The BP2 fulfills all requirements to meet the handset success factors in the entry and basic phone segment: lowest-cost electronic bill-of-material, smallest PCB size area and a hardware independent application and MMI development platform. Therefore handset manufacturers can completely concentrate on handset differentiation factors like design, product variants, MMI styles etc.



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Mobile Solutions



Never stop thinking.

BP2 Modem Functions

Standards

- GSM/GPRS Dualband
- Triband & Quadband options
- RF Band: 850/900/1800/1900 MHz
- Protocol stack GSM/GPRS Rel. 97

Voice Features

- Telephony
- Vocoders: HR, FR, EFR, AMR
- Echo cancellation
- Noise suppression

Data Features

- GPRS class B, multi-slot class 10, coding scheme CS 1..4
- CSD 9.6 kbit/s
- SMS MO/MT, cell broadcast
- AT command set
- Fax class 2
- STK class 3

Supported Applications

Common SW Feature Set

- WAP 2.0
- EMS Rel. 5
- MMS Rel. 1.1
- Java MIDP 1.0
- Integrated polyringer 32 voices @ 16 kHz
- Predictive text input
- Voice dialling & command

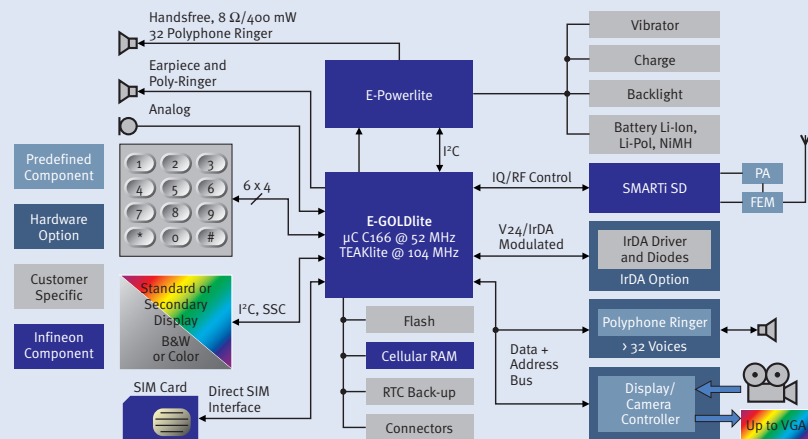
Optional Hardware Features

- IrDA 115 kbit/s
- Stereo FM radio
- Polyphone ringer more than 40 voices
- Integrated camera

System Architecture of BP2

Key Components

- Baseband E-GOLDlite
- Power management E-Powerlite
- RF transceiver SMARTi SD
- 16 – 32 Mbit Cellular RAM



Highest Integrated GSM/GPRS Platform

Leading low-cost GSM/GPRS platform for basic & entry level terminals

- 140 components (without customer specific parts)
- Leading edge eBOM
- CMOS RF transceiver
- Comprehensive feature set built-in

Smallest system PCB size

- Modem 10 cm²
- Flip-chip baseband, 8 x 8 mm

APOXI™ Application Framework

The APOXI™ Application Framework enables and includes

- A platform independent, easily reusable environment for rapid development and cost efficient solutions
- A powerful reference MMI with a broad range of pre-integrated reference applications
- An open API to enable unlimited 3rd party applications
- APIs for SIM, NVRAM, Flash, Display, Audio, Video, Real Time Operating Systems and the TCP/UDP family
- An object-oriented framework, ideal for developing customized “Look & Feel” MMIs & applications
- Support for Java, camera, and a broad range of advanced multimedia codecs
- An innovative roadmap of advanced applications provided by a leading developer network

How to reach us:

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Information

For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office.

Warnings

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies Office.

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